

9-15-08

DELPHI TECHNOLOGIES, INC.  
Customer Number 22851  
Legal Staff  
P.O. Box 5052  
Mail Code: 480-410-202  
Troy, Michigan 48007-5052

09-29-2008



103527142

Mail Stop Assignment Recordation Services  
Director of the United States Patent and Trademark Office  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Enclosed for recording is Assignment documentation for the following patent application:

Attorney Docket No.: DP-317731

(1) Assignor/Inventors: MICHAEL J. LOWRY; ERIC A BRAUER;  
THOMAS A. DEGENKOLB; and VICTOR WONG

(2) Assignee: DELPHI TECHNOLOGIES, INC.  
Legal Staff  
P.O. Box 5052  
Mail Code: 480-410-202  
Troy, Michigan 48007-5052

(3) Assignment of patent application

(4) Application number:

If blank, this documentation is filed together with the patent application.

(5) Address correspondence to: JIMMY L. FUNKE  
DELPHI TECHNOLOGIES, INC.  
Customer Number 22851  
Legal Staff  
P.O. Box 5052  
Mail Code: 480-410-202  
Troy, Michigan 48007-5052

(6) Number of applications: 1  
Total Fee: 40.00

Date documentation executed: 9/9/08; 9/9/08; 9/9/08; and 9/9/08.

(8) Not applicable

(9) To the best of my knowledge and belief, the information contained on this cover sheet is true and correct and any copy submitted is a true copy of the original document.

Title: LEADED SEMICONDUCTOR POWER MODULE WITH DIRECT  
BONDING AND DOUBLE SIDED COOLING

Please charge the \$ 40.00 assignment recordal fee to Delphi Technologies, Inc. Deposit Account No. 50-0831.

JIMMY L. FUNKE  
09/28/2008 08:10:19 00000024 500031 12283647  
01 FC:0021 40.00 DA

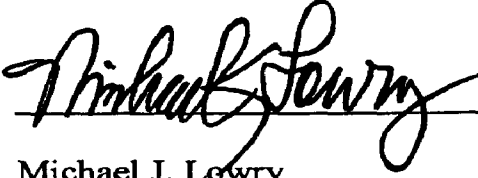
Total number of pages including cover sheet, attachments and document: 3  
Enclosures

# ASSIGNMENT

Pursuant to an agreement with my employer, I formally assign to DELPHI TECHNOLOGIES INC., the entire right, title and interest, in all countries, in the improvements set forth in the United States patent application entitled


## LEADED SEMICONDUCTOR POWER MODULE WITH DIRECT BONDING AND DOUBLE SIDED COOLING

for which I executed a declaration dated as indicated below.

Inventor's signature   
 FULL NAME: Michael J. Lowry  
 Residence: Indianapolis, Indiana


DATE: September 9, 2008

Declaration dated :  
September 9, 2008

Inventor's signature   
 FULL NAME: Eric A. Brauer  
 Residence: Avon, Indiana

DATE: Sept 9, 2008

Declaration dated :  
Sept 9, 2008

Inventor's signature   
 FULL NAME: Thomas A. Degenkolb  
 Residence: Noblesville, Indiana

DATE: SEPT 9, 2008

Declaration dated :  
SEPT 9, 2008

Inventor's signature \_\_\_\_\_  
 FULL NAME: Victor C.M. Wong  
 Residence: Singapore, Singapore

DATE: \_\_\_\_\_

Declaration dated :  
 \_\_\_\_\_

## ASSIGNMENT

Pursuant to an agreement with my employer, I formally assign to DELPHI TECHNOLOGIES INC., the entire right, title and interest, in all countries, in the improvements set forth in the United States patent application entitled

LEADED SEMICONDUCTOR POWER MODULE  
WITH DIRECT BONDING AND DOUBLE SIDED COOLING

for which I executed a declaration dated as indicated below.

Inventor's signature \_\_\_\_\_

DATE: \_\_\_\_\_

FULL NAME: Michael J. Lowry

Declaration dated : \_\_\_\_\_

Residence: Indianapolis, Indiana

Inventor's signature \_\_\_\_\_

DATE: \_\_\_\_\_

FULL NAME: Eric A Brauer

Declaration dated : \_\_\_\_\_

Residence: Avon, Indiana

Inventor's signature \_\_\_\_\_

DATE: \_\_\_\_\_

FULL NAME: Thomas A. Degenkolb

Declaration dated : \_\_\_\_\_

Residence: Noblesville, Indiana

Inventor's signature C. M. Wong

DATE: 09 Sept 2008

FULL NAME: Victor C.M. Wong

Declaration dated : \_\_\_\_\_

Residence: Singapore, Singapore

09 Sept 2008.